

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A process for manufacturing a flexible wiring board comprising forming a wiring pattern and a reinforcing guide pattern by etching a metal foil on an insulating substrate.

2. (Previously Presented) A flexible wiring board comprising a wiring pattern formed of a desired metal on an insulating substrate and a reinforcing guide pattern on the insulating substrate, wherein the reinforcing guide pattern is of the same metal as that of the wiring pattern, and wherein the reinforcing guide pattern has guide holes for positioning.

3. (Original) The flexible wiring board according to claim 2 wherein the guide pattern has a projecting reinforcing guide having a thickness greater than that of the wiring pattern.

4. (Original) The flexible wiring board according to claim 2 wherein the guide pattern is formed as a frame shape surrounding the periphery of the wiring pattern.

5. (Original) The flexible wiring board according to claim 3 wherein the guide pattern is formed as a frame shape surrounding the periphery of the wiring pattern.

6. (Original) The flexible wiring board according to claim 2 wherein the wiring pattern is formed a plurality of wiring patterns in a desired arrangement and the guide pattern is formed as a grid shape.

7. (Original) The flexible wiring board according to claim 3 wherein the wiring pattern is formed as a plurality of wiring patterns in a desired arrangement and the guide pattern is formed as a grid shape.

8. (Canceled)

9. (Canceled)

10. (Original) The flexible wiring board according to claim 6 wherein the guide pattern has guide holes for positioning.

11. (Original) The flexible wiring board according to claim 7 wherein the guide pattern has guide holes for positioning.

12. (Original) The flexible wiring board according to claim 2 wherein the wiring pattern has projecting electrodes.

13. (Original) The flexible wiring board according to claim 2 wherein the wiring pattern has flat electrodes.

14. (Currently Amended) The flexible wiring board according to claim 2 wherein a first wiring pattern is formed on one side of the insulating substrate, and a second wiring pattern is formed on an opposite side of the insulating substrate to the wiring pattern.

15. (Original) The flexible wiring board according to claim 14 wherein the second wiring pattern has projecting electrodes.

16. (Original) The flexible wiring board of claim 14 wherein the second wiring pattern has flat electrodes.

17. (Currently Amended) The flexible wiring board according to claim 2 wherein the reinforcing guide pattern is ~~formed integral~~ integrally formed with the wiring pattern on the insulating substrate.